

Compound copper-aluminium wire and its production process

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Abstract of CN1230754

The compound wire consists of coated copper layer and aluminum core, which are metallurgically combined firmly through solid phase combination process without formed harmful fragile intermediate compound. The compound wire of the present invention has high conductivity, low specific weight, low contact resistance and cost greatly lower than that of copper wire. It may be used as a substitute of pure copper wire and pure aluminum wire widely in power and electronic industry.

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